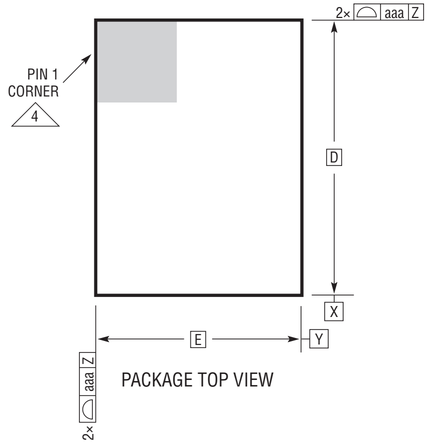
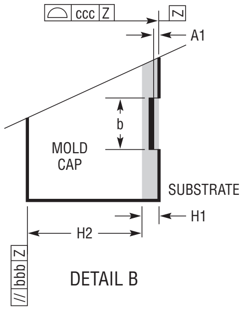
ANALOG DEVICES | POWER BY LINEAR

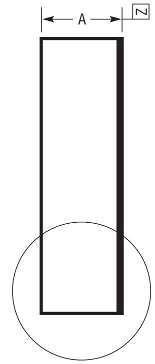
LGA Package
24-Lead (3mm × 4mm × 1.18mm)
(Reference LTC DWG# 05-08-1657 Rev A)



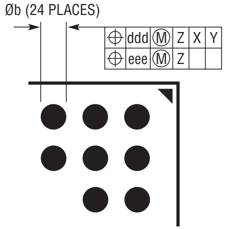
PACKAGE TOP VIEW



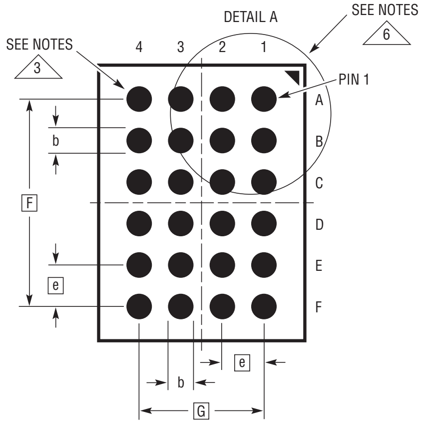
DETAIL B



DETAIL B
PACKAGE SIDE VIEW

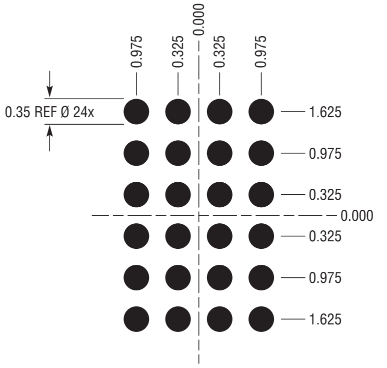


DETAIL A



PACKAGE BOTTOM VIEW

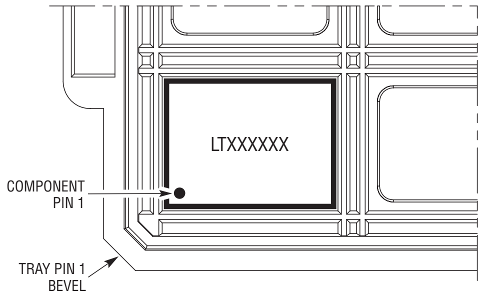
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. PAD DESIGNATION PER JEP95
4. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS

SYMBOL	MIN	NOM	MAX	NOTES
A	1.08	1.18	1.28	
A1			0.03	
b	0.32	0.35	0.38	PAD DIMENSION
D		4.00		
E		3.00		
e		0.65		
F		3.25		
G		1.95		
H1		0.18 REF		SUBSTRATE THK
H2		1.00 REF		MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.10	
ddd			0.15	
eee			0.08	
TOTAL NUMBER OF PADS: 24				



PACKAGE IN TRAY LOADING ORIENTATION

LGA 24 0319 REV A